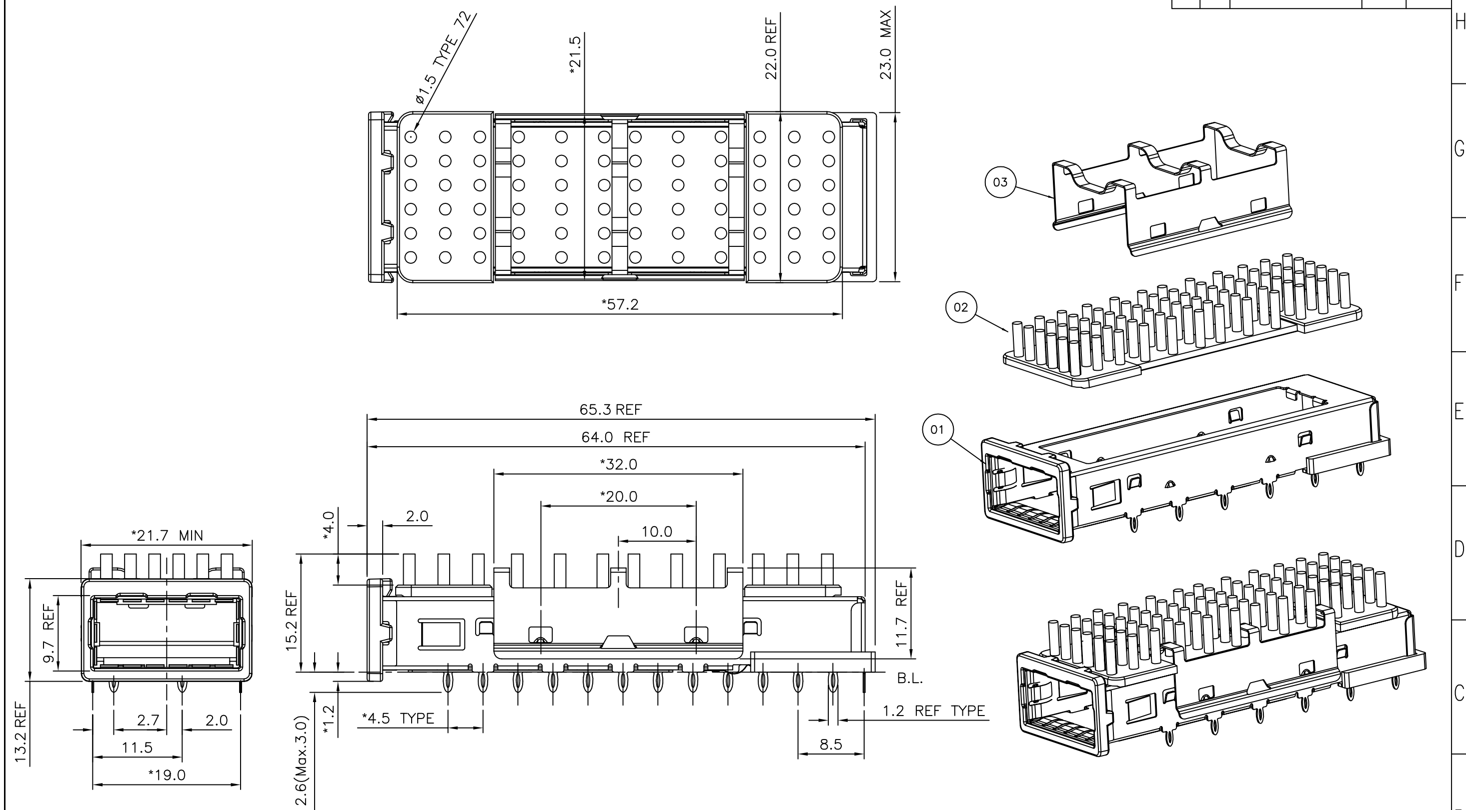
A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



PART NUMBER: XFP002-L

No.	DESCRIPTION	Q'ty	MATERIAL	PLATING	REMARK
01	XFP CAGE ASSEMBLY (Non-Logo)	1			
02	XFP HEAT SINK (4.00mm)	1	AL	Ni	
03	XFP HEAT SINK CLIP	1	SUS		

DETACHED LISTS

MM (INCH)

TOLERANCES EXCEPT AS NOTED

MM	
.0 ± 0.2	±
.00 ± 0.15	±
.000 ± 0.075	±

ANGLES ± 0.5

THIRD ANGLE PROJECTION

DFTO	tzou	DATE	06/02/06'
CHKD		DATE	
MFO		DATE	
APPVL		DATE	

MATERIAL :

QT'Y :

FINISH :

SCALE : 1 : 2

FULL RISE ELECTRONIC CO., LTD

TITLE (Non-Logo)

XFP CAGE WITH PCI HEAT SINK KIT

DRAWING NO. XFP002-L

/PART NO. SEE NOTE

SIZE A3 REV 0

DO NOT SCALE DRAWING SHEET 1 OF 2

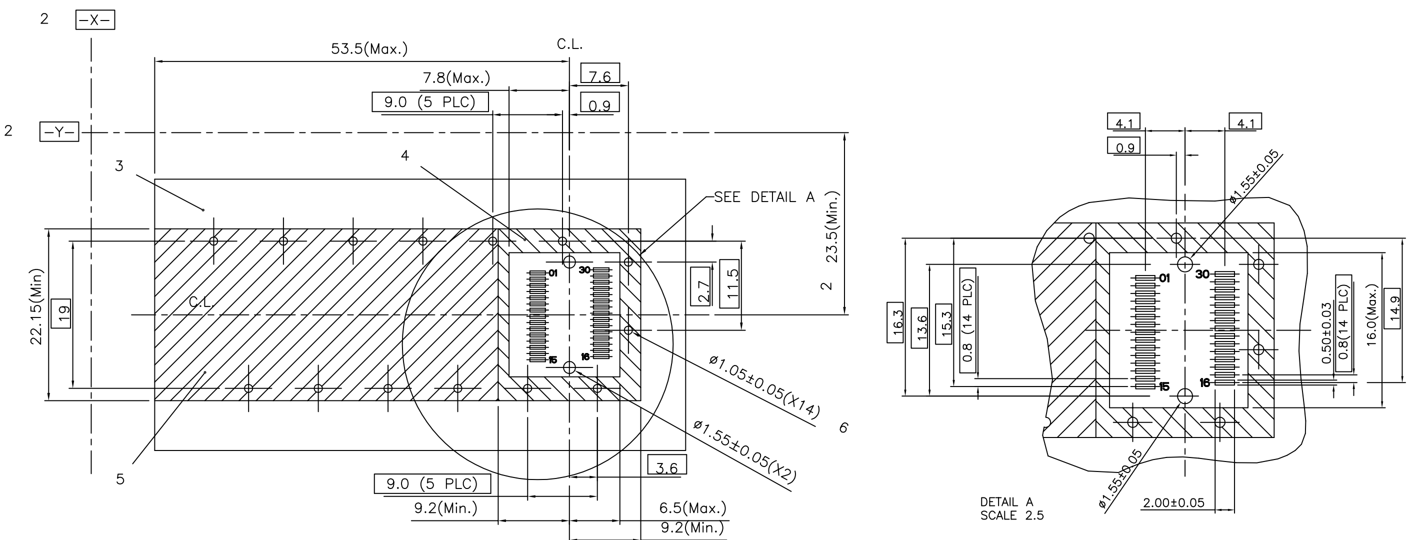
H G F E D C B A

8 7 6 5 4 3 2 1

Downloaded from Elcodis.com electronic components distributor

A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



RECOMMEND P.C.B. LAYOUT

Note:

1. DESIGN MEETS REQUIREMENTS OF XFPMSA SPECIFICATION REV. 3.1 (10 GIGABIT SMALL FROM FACTOR PLUGGABLE MODULE).
2. DATUM -X- AND -Y- ESTABLISHED BY CUSTOMER.
3. DATUM -A- IS TOP SURFACE OF HOST BOARD.
4. INDICATED SURFACES TO BE CONDUCTIVE AND CONNECTED TO CHASSIS GROUND.
5. CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)
6. RECOMMENDATION FOR P.C.BOARD HOLES:
   A. HOLE ø AFTER DRILLING : 1.15±0.02 mm.
   B. HOLE ø Sn PLATE : 1.05±0.05 mm.
   C. 25um ~ 50um COPPER UNDERPLATE.
7. -CAUTION- REFLOW PROCESS WILL DAMAGE CAGE ASSEMBLY.

MM (INCH)		DFTO tzou	DATE 06/02/06'
TOLERANCES EXCEPT AS NOTED		CHKD	DATE
MM		MFO	DATE
.0 ± 0.2	±	APPVL	DATE
.00 ± 0.15	±		
.000 ± 0.075	±	MATERIAL :	
ANGLES ± 0.5		QT'Y :	
THIRD ANGLE PROJECTION		FINISH :	
		SCALE : 1 : 2	

DETACHED LISTS

FULL RISE ELECTRONIC CO., LTD

TITLE (Non-Logo)

XFP CAGE WITH PCI HEAT SINK KIT

DRAWING NO. XFP002-L	SIZE	REV
/PART NO. SEE NOTE	A3	0
DO NOT SCALE DRAWING	SHEET 2	OF 2

Downloaded from Elcodis.com electronic components distributor